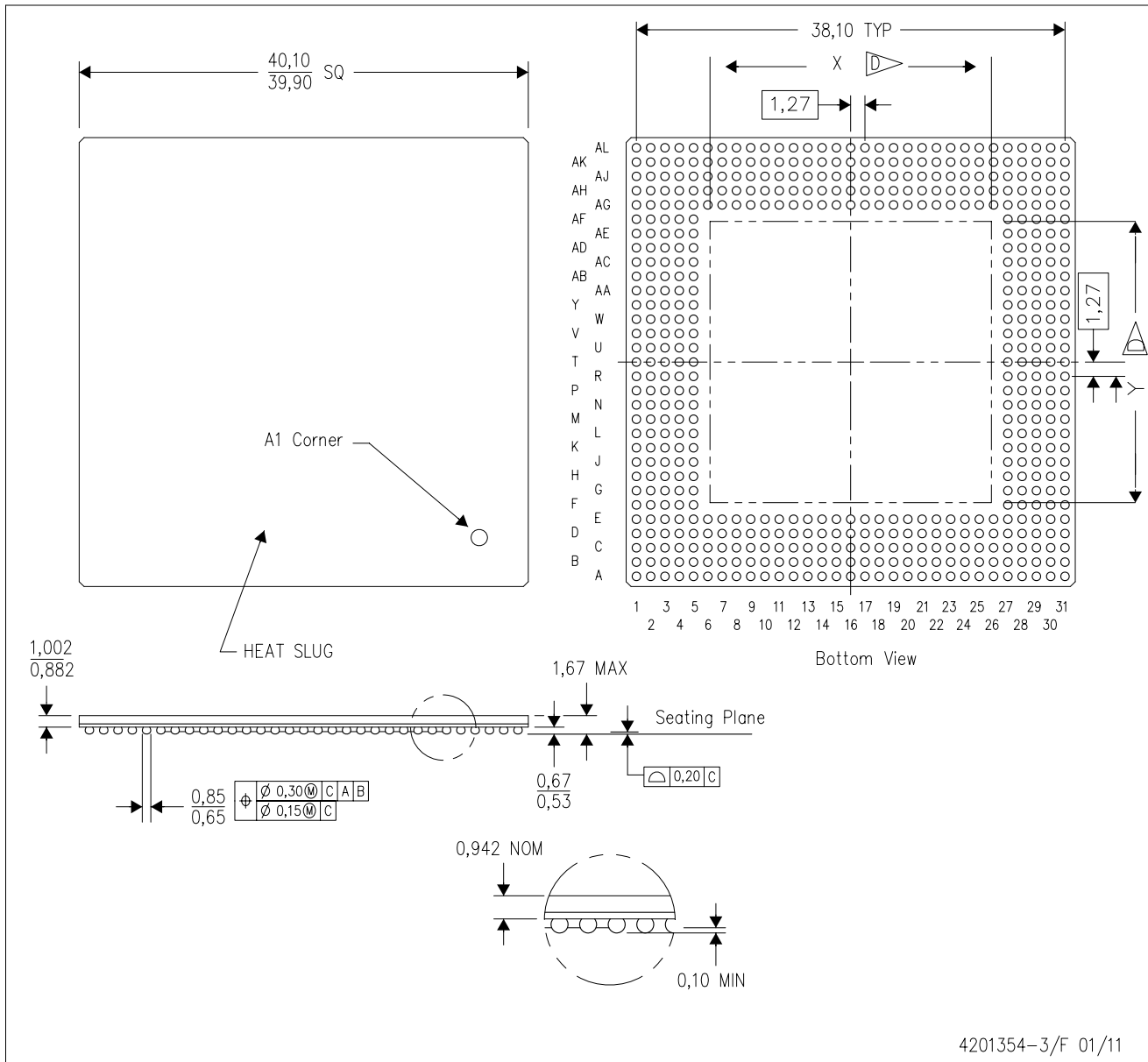


MECHANICAL DATA

GPG (S-PBGA-N520)

PLASTIC BALL GRID ARRAY (CAVITY DOWN)



4201354-3/F 01/11

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Thermally enhanced plastic package with heat slug (HSL).
 - $\triangle D$ The encapsulation size (X,Y) will vary with cavity size. The distance from bond finger edge to encapsulation shall be min 0.50mm.

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